

# SN54ABT5402A, SN74ABT5402A 12-BIT LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

SCBS660B – FEBRUARY 1996 – REVISED MAY 1997

- **Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required**
- **State-of-the-Art EPIC-II<sup>™</sup> BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C**
- **Typical V<sub>OLV</sub> (Output Undershoot) < 0.5 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C**
- **Package Options Include Plastic Small-Outline (DW) Package and Ceramic Chip Carriers (FK) and DIPs (JT)**

## description

These 12-bit buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

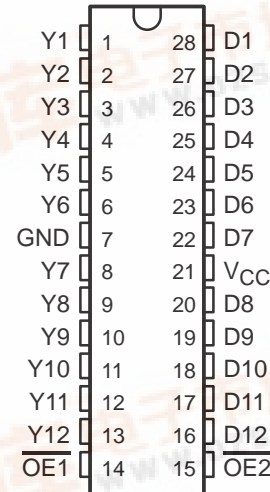
The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ( $\overline{OE1}$  or  $\overline{OE2}$ ) input is high, all 12 outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

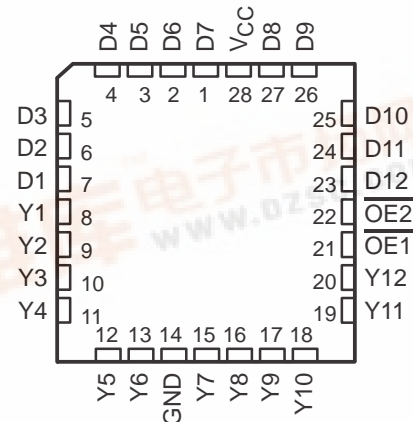
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT5402A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT5402A is characterized for operation from –40°C to 85°C.

SN54ABT5402A . . . JT PACKAGE  
SN74ABT5402A . . . DW PACKAGE  
(TOP VIEW)



SN54ABT5402A . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE

INPUTS			OUTPUT Y
$\overline{OE1}$	$\overline{OE2}$	D	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

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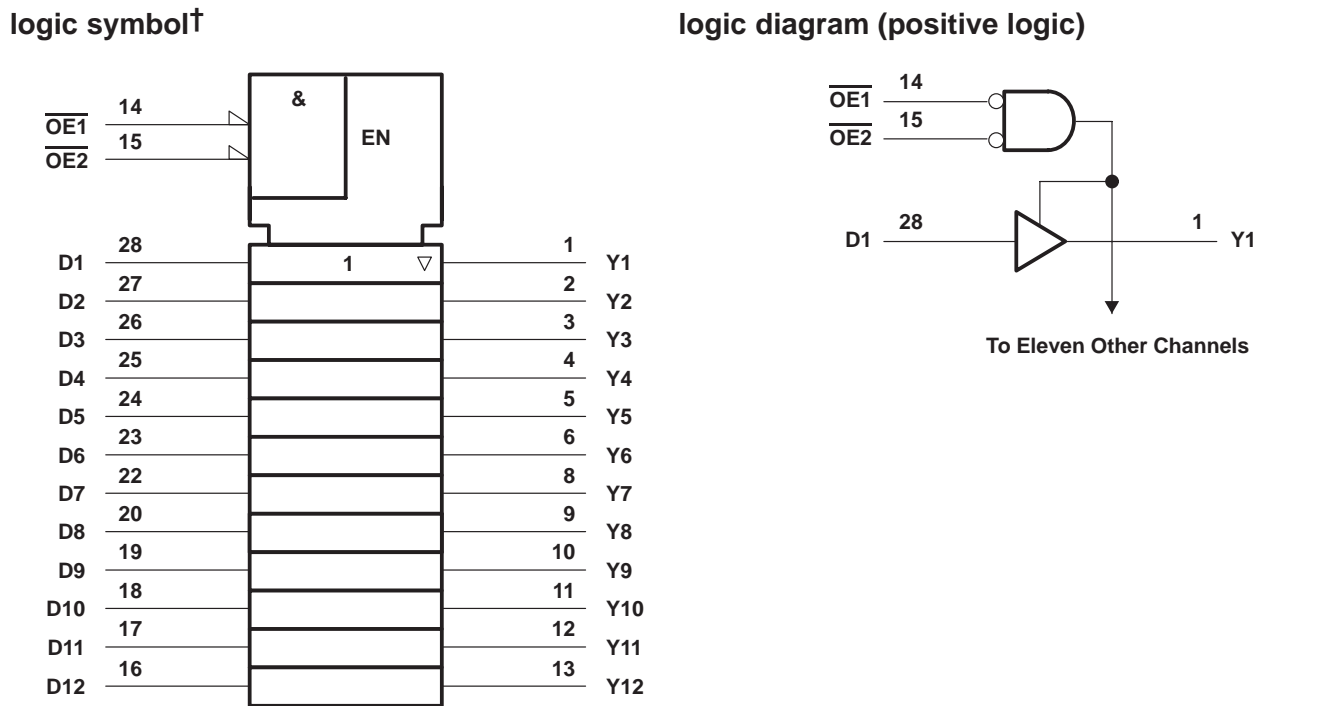
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† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.  
Pin numbers shown are for the DW and JT packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, $V_O$	–0.5 V to 5.5 V
Current into any output in the low state, $I_O$	30 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	78°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

# SN54ABT5402A, SN74ABT5402A 12-BIT LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 3)

		SN54ABT5402A		SN74ABT5402A		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.5	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		–12		–12	mA
I <sub>OL</sub>	Low-level output current		12		12	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled			10	ns/V
T <sub>A</sub>	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T <sub>A</sub> = 25°C			SN54ABT5402A		SN74ABT5402A		UNIT	
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
V <sub>IK</sub>		V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = –18 mA		–1.2			–1.2		–1.2		V	
V <sub>OH</sub>		V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = –1 mA		3.35	3.7		3.3		3.35		V	
		V <sub>CC</sub> = 5 V, I <sub>OH</sub> = –1 mA		3.85	4.2		3.8		3.85			
		V <sub>CC</sub> = 4.5 V		I <sub>OH</sub> = –3 mA				3		3.1		
				I <sub>OH</sub> = –12 mA		2.6				2.6		
V <sub>OL</sub>		V <sub>CC</sub> = 4.5 V		I <sub>OL</sub> = 8 mA					0.8		V	
				I <sub>OL</sub> = 12 mA					0.65			
V <sub>hys</sub>				100							mV	
I <sub>I</sub>		V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND		±1			±1		±1		μA	
I <sub>OZH</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V		10			10		10		μA	
I <sub>OZL</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.5 V		–10			–10		–10		μA	
I <sub>off</sub>		V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V		±100					±100		μA	
I <sub>CEX</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high	50			50		50		μA	
I <sub>O</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.5 V		–25	–45	–100	–25	–100	–25	–100	mA	
I <sub>OS</sub> ‡		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0		–50		–200	–50	–200	–50	–200	mA	
I <sub>CC</sub>		V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND		Outputs high		5	50	50		50		μA
				Outputs low		39	48	48		48		mA
				Outputs disabled		1	50	50		50		μA
ΔI <sub>CC</sub> §	Data inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND		Outputs enabled		1.5		1.5		1.5		mA
				Outputs disabled		0.05		0.05		0.05		
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND		1.5			1.5		1.5			
C <sub>i</sub>		V <sub>I</sub> = 2.5 V or 0.5 V		3							pF	
C <sub>O</sub>		V <sub>O</sub> = 2.5 V or 0.5 V		8							pF	

† All typical values are at V<sub>CC</sub> = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

# SN54ABT5402A, SN74ABT5402A

## 12-BIT LINE/MEMORY DRIVERS

### WITH 3-STATE OUTPUTS

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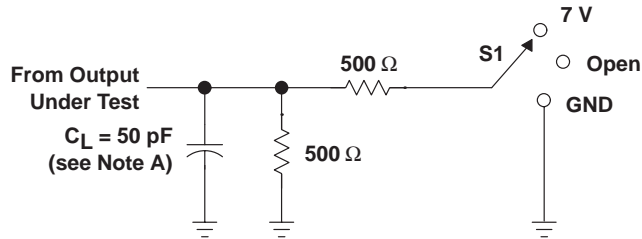
switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABT5402A		SN74ABT5402A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	D	Y	2	4.5	5.2	2	6.3	2	6.2	ns
$t_{PHL}$			1.5	3.7	5	1.5	5.7	1.5	5.6	
$t_{PZH}$	$\overline{OE}$	Y	2.5	5.7	7.6	2.5	8.8	2.5	8.7	ns
$t_{PZL}$			2	4.4	6.3	2	7.6	2	7.5	
$t_{PHZ}$	$\overline{OE}$	Y	1.5	3.6	4.4	1.5	5.5	1.5	5.2	ns
$t_{PLZ}$			1.5	4.2	5.4	1.5	7.4	1.5	6.9	

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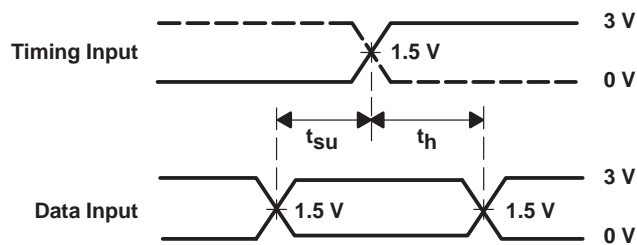
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## PARAMETER MEASUREMENT INFORMATION

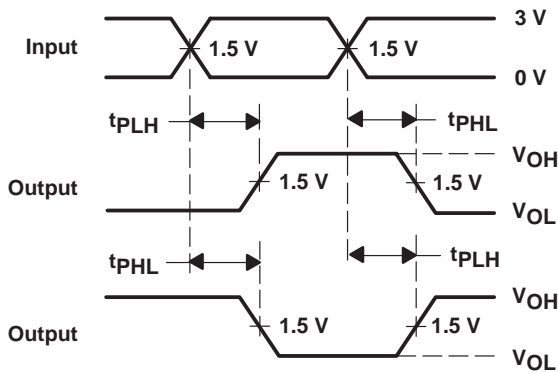


LOAD CIRCUIT

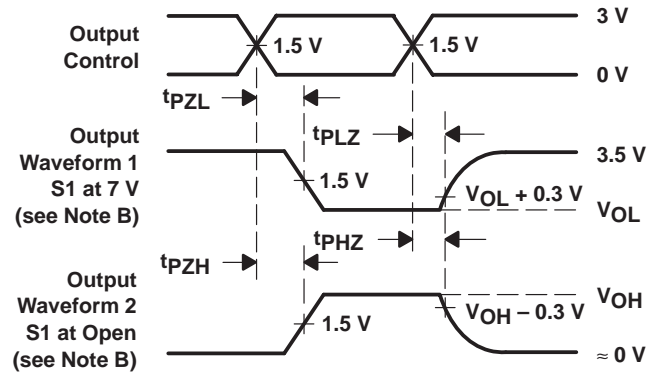
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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